

U.S. UTILITY Patent Application

PATENT NUMBER and
ISSUE DATE

APPL NUM	FILING DATE	CLASS	SUBCLASS	GAU	EXAMINER
10074718	02/13/2002	228	41	1725	Cooke

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****CONTINUING DATA VERIFIED:**

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**** FOREIGN APPLICATIONS VERIFIED:**
JAPAN 2001-039888 02/16/2001

PG-PUB DO NOT PUBLISH ☐

RESCIND ☐

Foreign priority claimed ☐ yes ☐ no
35 USC 119 conditions met ☐ yes ☐ no
Verified and Acknowledged Examiners's initials

ATTORNEY DOCKET NO

JP920000451US1

TITLE : Solder ball disposing apparatus, solder ball reflow apparatus, and solder ball bonding apparatus

U.S. DEPT. OF COMM./PAT. & TM.-PTO-436L (Rev. 12-94)

NOTICE OF ALLOWANCE MAILED		CLAIMS ALLOWED	
		Total Claims	Print Claim for O.G.
ISSUE FEE		DRAWING	
Amount Due	Date Paid	Sheets Drawn	Figs. Drawn
		Print Fig.	
TERMINAL DISCLAIMER		Application Examiner	
		PREPARED FOR ISSUE	
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